

SOT1661-1

FBGA621, plastic, fine-pitch ball grid array; 621 bumps; 0.8 mm pitch; 21 mm x 21 mm x 1.92 mm body

7 March 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA621
Package type industry code	FBGA621
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-01-2016
Manufacturer package code	98ASA00801D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	1.92	2.07	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	621	-	



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2 Package outline

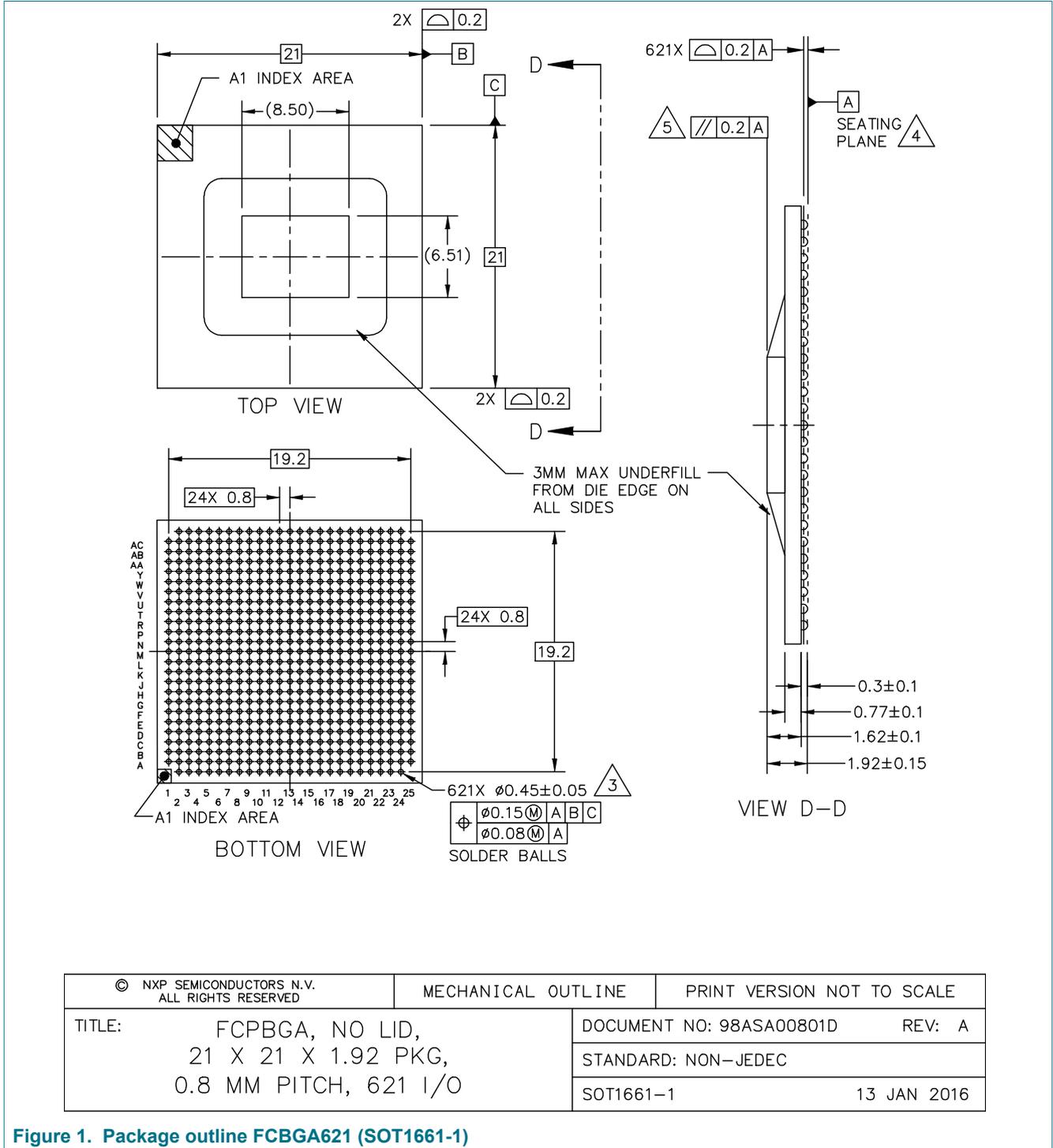


Figure 1. Package outline FCBGA621 (SOT1661-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: FCPBGA, NO LID, 21 X 21 X 1.92 PKG, 0.8 MM PITCH, 621 I/O	DOCUMENT NO: 98ASA00801D	REV: A
	STANDARD: NON-JEDEC	
	SOT1661-1	13 JAN 2016

Figure 2. Package outline note FCBGA621 (SOT1661-1)

3 Legal information

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